



Material Content Data Sheet



Sales Product Name				IPB016N06L3 G		Issued		25. September 2017	
MA#				MA000472884					
Package				PG-TO263-7-3		Weight*		1540.63 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	10.427	0.68	0.68	6768	6768	
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521		
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156		
	non noble metal	copper	7440-50-8	801.714	52.03	52.10	520380	521058	
wire	non noble metal	aluminium	7429-90-5	128.313	8.33	8.33	83286	83286	
encapsulation	organic material	carbon black	1333-86-4	7.100	0.46		4608		
	plastics	epoxy resin	-	78.099	5.07		50693		
	inorganic material	silicondioxide	60676-86-0	388.130	25.19	30.72	251930	307231	
leadfinish	non noble metal	tin	7440-31-5	12.471	0.81	0.81	8095	8095	
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175	
solder	noble metal	silver	7440-22-4	0.168	0.01		109		
	non noble metal	tin	7440-31-5	0.134	0.01		87		
	non noble metal	lead	7439-92-1	6.412	0.42	0.44	4162	4358	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	copper	7440-50-8	106.210	6.89	6.90	68939	69029	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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